# Correspondence to PB-free soldering





# Lead-free N<sub>2</sub> Reflow Soldering Machine

The model RF-460 is a small Reflow Soldering Machine corresponding to lead-free soldering and using infrared radiation and nitrogen (N2) for the basic heating. While this is a small table-top reflow machine, it a method with six far infrared (IR) zones, and the precise and stable temperature profile required for lead-free reflow soldering can be obtained. By use of far infrared radiation and nitrogen (N<sub>2</sub>), the various requirements for lead-free soldering can be met sufficiently. A max. temperature of 350°C and solder wettability are realized.

#### **Features**

- This is a table-top reflow soldering machine with correspondence to nitrogen (N<sub>2</sub>). Circuit boards up to 300×300mm can be processed.
- Rapid heating is performed with a 6-zone quartz heater using far infrared radiation and nitrogen (N<sub>2</sub>), and the desired temperature profile can be obtained.
- Precise temperature control (±0.3%) up to max. 350°C and stable temperature profiles can be obtained with a high-precision PID temperature controller.

## **Specifications**

• Heating section: 6 zones, W300mm×L780mm×H30mm (at the inlet). Heater: Quartz tube heater, IR (wavelength: 2 to 10 µm).

Upper part: Each zone: 0.6kW

Lower part: 1,2,5,6zone: 0.6kW / 3,4zone: 0.3kW

Heating method : IR + N<sub>2</sub> system

Temperature control: Max. 350°C ±0.3%, P.I.D. temperature controller. Temperature control for the atmosphere in the upper part of the

furnace for each zone.

 Conveyor : W 300 mm, SUS mesh belt. 90 to 1400 mm/min

Conveyor direction:  $R \rightarrow L$  or  $L \rightarrow R$  (at user's request)

Digital speed controller

 Cooling : Forced cooling by a fan on the outlet side

200V 6.7kW / 220V 7.8kW, 50/60 Hz Power supply: Single phase

• N<sub>2</sub> supply quantity : About 20 to 50l/min

(Oxygen density: about 1000 ppm).

 Safety devices : Leak/Over-current circuit breaker,

> Emergency stop switch, Alarm output (over/under temperature / heater disconnection)

• External dimensions: (W)1500×(D)590×(H)640mm,

 Weight : about 150kg.

## Applicable circuit boards

 Dimensions : 15mm×15mm to 300mm×300mm

• Board thickness : 0.125mm to 2mm

: Max. 30mm Height

### Applications

- Reflow soldering of SMT circuit boards.
- · Lead-free reflow soldering.
- Drying of thermosetting adhesives and other heating work.

\*Specifications subject to change without notice.

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